FEATURES

- Input accepts virtually all logic standards:
 - Single-ended: SSTL, TTL, CMOS
 - · Differential: LVDS, HSTL, CML
- **■** Guaranteed AC parameters over temperature:
 - f_{MAX} > 2.5Gbps (2.5GHz toggle)
 - $t_r / t_f < 200 ps$
 - Within-device skew < 50ps
 - Propagation delay < 400ps
- Low power: 46mW/channel (typ)
- 3.0V to 3.6V power supply
- 100K LVPECL outputs
- Flow-through pinout and fully differential design
- Two channels in a 10-pin (3mm x 3mm) MSOP package

SuperLite™

DESCRIPTION

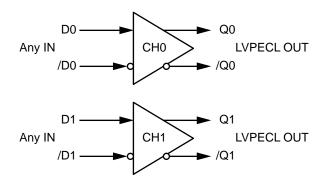
The SY55857L is a fully differential, high-speed dual translator optimized to accept any logic standard from single-ended TTL/CMOS to differential LVDS, HSTL, or CML and translate it to LVPECL. Translation is guaranteed for speeds up to 2.5Gbps (2.5GHz toggle frequency). The SY55857L does not internally terminate its inputs, as different interfacing standards have different termination requirements.

All support documentation can be found on Micrel's web site at www.micrel.com.

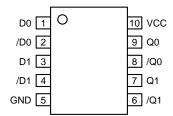
APPLICATIONS

- **■** High-speed logic
- Data communications systems
- **■** Wireless communications systems
- **■** Telecom systems

FUNCTIONAL BLOCK DIAGRAM



PACKAGE/ORDERING INFORMATION



10-Pin MSOP (K10-1)

Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY55857LKI	K10-1	Industrial	857L	Sn-Pb
SY55857LKITR ⁽²⁾	K10-1	0-1 Industrial 857L		Sn-Pb
SY55857LKG ⁽³⁾	K10-1	Industrial	857L with Pb-Free bar line indicator	NiPdAu Pb-Free
SY55857LKGTR ^(2, 3)	K10-1	Industrial		

Notes:

- 1. Contact factory for die availability. Dice are guaranteed at T_A = 25°C, DC Electricals only.
- 2. Tape and Reel.
- 3. Pb-Free package recommended for new designs.

PIN DESCRIPTIONS

Pin Number	Pin Name	Description
D0, /D0	1, 2	Channel 0 Differential Inputs (clock or data). See Figure 2 for input structure. See "Input Interface" section for typical interface recommendations.
D1, /D1	3, 4	Channel 1 Differential Inputs (clock or data). See Figure 2 for input structure. See "Input Interface" section for typical interface recommendations.
Q0, /Q0	9, 8	Channel 0 Differential 100k-compatible LVPECL Outputs. Terminate to V_{CC} – 2V. See "LVPECL Output Termination" section. Outputs are low impedance, emitter-followers. For AC-coupled applications, a pull-down resistor is required on Q and /Q to ensure a DC current path to GND.
Q1, /Q1	7, 6	Channel 1 Differential 100k-compatible LVPECL Outputs. Terminate to V _{CC} – 2V. See "LVPECL Output Termination" section. Outputs are low impedance, emitter-followers. For AC-coupled applications, a pull-down resistor is required on Q and /Q to ensure a DC current path to GND.
GND	5	Device Ground. Typically connected to Logic ground.
V _{cc}	10	Supply Voltage. Typically connect to +3.3V $\pm 10\%$ supply. Bypass with $0.01\mu F \mid 0.1\mu F$ low ESR capacitors.

Absolute Maximum Ratings(1)

Power Supply Voltage (V _{CC})	0.5V to +6.0V
Input Voltage (V _{IN})	$-0.5V$ to $V_{CC} + 0.5V$
Output Current (I _{OUT})	
Continuous	50mA
Surge	100mA
Lead Temperature (soldering, 20 sec.)	+260°C
Storage Temperature Range (T _S)	65°C to +150°C

Operating Ratings⁽²⁾

Power Supply Voltage (V _{CC})	+3.0V to +3.6V
Ambient Temperature Range (T _A)	40°C to +85°C
Package Thermal Resistance ⁽³⁾	
$MSOP(\theta_{JA})$	
Still-Air	113°C/W
500lpfm	96°C/W
$MSOP(\theta_{JC})$	
Junction-to-Case	42°C/W

DC ELECTRICAL CHARACTERISTICS(4)

 $T_A = -40^{\circ}C$ to +85°C; unless noted.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{CC}	Power Supply Voltage		3.0	3.3	3.6	V
I _{CC}	Power Supply Current	Inputs/outputs open		28	45	mA

INPUT ELECTRICAL CHARACTERISTICS(4)

 V_{CC} = +3.0V to +3.6V; GND = 0V; T_A = -40°C to +85°C; unless noted.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V_{ID}	Input Voltage Swing	See Figure 1a, V _{IN} < 2.4V.	100			mV
		V _{IN} < V _{CC} +0.3V	200			mV
V_{IH}	Input HIGH Voltage				V _{CC} +0.3	V
$V_{\rm IL}$	Input LOW Voltage		-0.3			V

(100K) LVPECL OUTPUT CHARACTERISTICS(5)

 V_{CC} = +3.0V to +3.6V; GND = 0V; T_{Δ} = -40°C to +85°C; R_{L} = 50 Ω to V_{CC} -2V, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{OL}	Output LOW Voltage Q, /Q		V _{CC} -1.945	V _{CC} -1.820	V _{CC} -1.695	V
V _{OH}	Output HIGH Voltage Q, /Q		V _{CC} -1.145	V _{CC} -1.020	V _{CC} -0.895	V
V _{OUT}	Output Voltage Swing Q, /Q	See Figure 1a.	550	800		mV
V _{DIFF_OUT}	Differential Output Voltage Swing Q, /Q	See Figure 1b.	1100	1600		mV _{pp}

Notes:

- 1. Permanent device damage may occur if the ratings in "Absolute Maximum Ratings" section are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- 3. Package thermal resistance assumes exposed pad is soldered (or equivalent) to the device's most negative potential (GND) on the PCB. ψ_{JB} uses 4-layer θ_{JA} in still air unless otherwise stated.
- 4. The specifications shown are valid after thermal equilibrium has been established.
- 5. 100K circuits are designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

AC ELECTRICAL CHARACTERISTICS

 V_{CC} = 3.3V ±10%; T_A = -40°C to +85°C; R_L = 50 Ω to V_{CC} -2V, unless otherwise stated.

Symbol	Parameter	Condition		Min	Тур	Max	Units
f _{MAX}	Maximum Operating Frequency	V _{IN} < 2.4V NRZ Da	ta	2.5			Gbps
	Note 6	V _{IN} < 2.4V Clo	ck	2.5			GHz
		V _{IN} < V _{CC} +0.3V NRZ Da	ta	1.25			Gbps
		V _{IN} < V _{CC} +0.3V Clo	ck	1.25			GHz
t _{PD}	Propagation Delay D-to-Q					400	ps
tSKEW	Within-Device-Skew (Differential)	Note 7				50	ps
	Part-to-Part Skew (Differential)	Note 8				200	ps
t _{JITTER}	Random Jitter (RJ)	Note 9				1	ps _{RMS}
	Deterministic Jitter (DJ)	Note 10				10	ps _{PP}
	Total Jitter (TJ)	Note 11			1	10	ps _{PP}
t _r , t _f	Output Rise/Fall Time 20% to 80%	At full output swing				200	ps

Notes:

- Clock frequency is defined as the maximum toggle frequency, and guaranteed for functionality only. Measured with a 750mV signal, 50% duty cycle and V_{OLT} swing ≥ 400mV. High -frequency AC-parameters are guaranteed by design and characterization.
- 7. Within-device skew is measured between two different outputs under identical transitions.
- 8. Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.
- 9. Random jitter is measured with a K28.7 comma detect character pattern, measured at 2.5Gbps.
- 10. Deterministic jitter is measured at 2.5Gbps with both K28.5 and 2²³–1 PRBS pattern.
- 11. Total jitter definition: with an ideal differential clock input of frequency ≤ f_{MAX}, no more than one output edge in 10¹² output edges will deviate by more than the specified peak-to-peak jitter value.

SINGLE-ENDED AND DIFFERENTIAL SWINGS

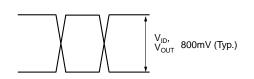


Figure 1a. Single-Ended Voltage Swing

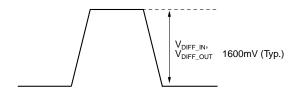


Figure 1b. Differential Voltage Swing

FUNCTIONAL DESCRIPTION

Establishing Static Logic Inputs

Do not leave unused inputs floating. Tie either the true or complement inputs to ground, but not both. A logic zero is achieved by connecting the complement input to ground with the true input floating. For a TTL input, tie a $2.5 k\Omega$ resistor between the complement input and ground. See "Input Interface" section.

Input Levels

LVDS, CML and HSTL differential signals may be connected directly to the D inputs. Depending on the actual worst case voltage seen, performance of SY55857L varies as per the following table:

Input Voltage Range	Minimum Voltage Swing	Maximum Translation Speed			
0 to 2.4V	100mV	2.5Gbps			
0 to V _{CC} +0.3	200mV	1.25Gbps			

Table 1. Input Voltage Swings

For LVDS applications, only point-to-point interfaces are supported. Due to the current required by the input structure shown in Figure 2, mutli-drop and multi-point architectures are not supported.

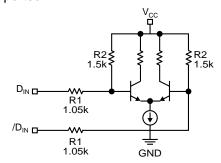


Figure 2. Simplified Input Structure

INPUT INTERFACE

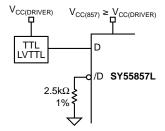


Figure 3. 3.3V "TTL"

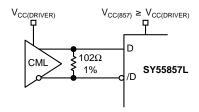


Figure 4. CML-DC Coupled

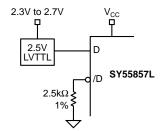


Figure 5. 2.5V "TTL"

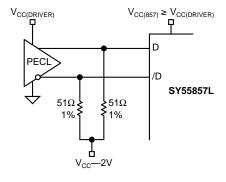


Figure 6. PECL-DC Coupled

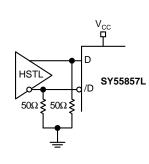


Figure 7. HSTL

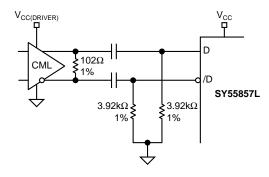


Figure 8. CML-AC Coupled Short Lines

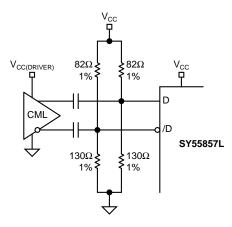


Figure 9. CML-AC Coupled Long Lines

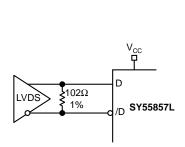


Figure 10. LVDS

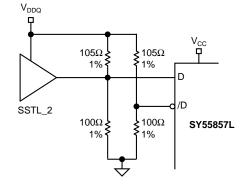


Figure 11. SSTL 2

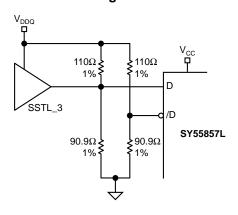


Figure 12. SSTL_3

LVPECL OUTPUT TERMINATION

LVPECL output have very low output impedance (open emitter), and small signal swing which results in low EMI. LVPECL is ideal for driving 50Ω and 100Ω -controlled impedance transmission lines. There are several techniques in terminating the LVPECL output, as shown in Figures 13 through 15.

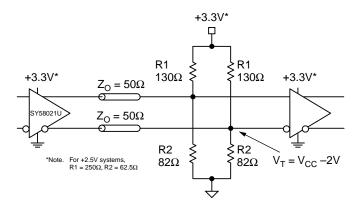


Figure 13. Parallel Termination-Thevenin Equivalent

Notes:

- 1. For +2.5V systems: R1 = 250Ω , R2 = 62.5Ω .
- 2. For +3.3V systems: R1 = 130Ω , R2 = 82Ω .

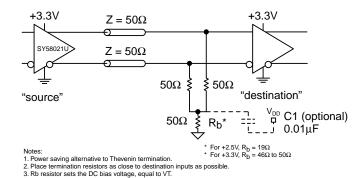


Figure 14. Three-Resistor "Y-Termination"

Notes:

- 1. Power-saving alternatives to Thevenin termination.
- 2. Place termination resistors as close to destination inputs as possible.
- 3. Rb resistor sets the DC bias voltage, equal to $\rm V_{\rm T}.$

For +2.5V systems: $R_b = 19\Omega$.

For +3.3V systems: $R_b = 46\Omega$ to 50Ω .

4. C1 is an optional bypass capacitor intended to compensate for any $t_{\text{r}}/t_{\text{f}}$ mismatches.

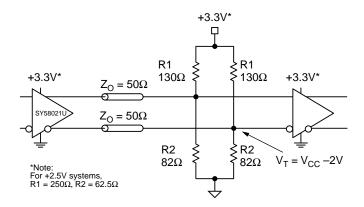


Figure 15. Terminating Unused I/O

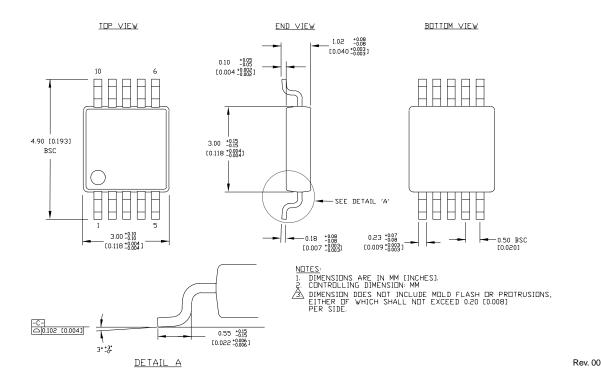
Notes:

- 1. Unused output (/Q) must be terminated to balance the output.
- 2. For +2.5V systems: R1 = 250 Ω , R2 = 62.5 Ω , R3 = 1.25k Ω , R4 = 1.2k Ω

For +3.3V systems: R1 = 130Ω , R2 = 82Ω , R3 = $1k\Omega$, R4 = $1.6k\Omega$.

3. Unused output pairs (Q and /Q) may be left floating.

10-PIN MSOP (K10-1)



MICREL, INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA

TEL + 1 (408) 944-0800 FAX + 1 (408) 474-1000 WEB http://www.micrel.com

The information furnished by Micrel in this data sheet is believed to be accurate and reliable. However, no responsibility is assumed by Micrel for its use.

Micrel reserves the right to change circuitry and specifications at any time without notification to the customer.

Micrel Products are not designed or authorized for use as components in life support appliances, devices or systems where malfunction of a product can reasonably be expected to result in personal injury. Life support devices or systems are devices or systems that (a) are intended for surgical implant into the body or (b) support or sustain life, and whose failure to perform can be reasonably expected to result in a significant injury to the user. A Purchaser's use or sale of Micrel Products for use in life support appliances, devices or systems is at Purchaser's own risk and Purchaser agrees to fully indemnify Micrel for any damages resulting from such use or sale.

© 2005 Micrel, Incorporated.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Translation - Voltage Levels category:

Click to view products by Microchip manufacturer:

Other Similar products are found below:

NLSX4373DMR2G NLSX5012MUTAG NLSX0102FCT2G NLSX4302EBMUTCG PCA9306FMUTAG MC100EPT622MNG
NLSX5011MUTCG NLV9306USG NLVSX4014MUTAG NLSV4T3144MUTAG NLVSX4373MUTAG NB3U23CMNTAG
MAX3371ELT+T NLSX3013BFCT1G NLV7WBD3125USG NLSX3012DMR2G 74AVCH1T45FZ4-7 NLVSV1T244MUTBG
74AVC1T45GS-Q100H CLVC16T245MDGGREP MC10H124FNG CAVCB164245MDGGREP CD40109BPWR MC10H350FNG
MC10H125FNG MC100EPT21MNR4G MC100EP91DWG NLSX3018MUTAG NLSV2T244MUTAG NLSX3013FCT1G
NLSX5011AMX1TCG PCA9306USG SN74GTL1655DGGR SN74AVCA406LZQSR NLSX4014DTR2G NLSX3018DTR2G
LTC1045CSW#PBF LTC1045CN#PBF SY100EL92ZG 74AXP1T34GMH 74AXP1T34GNH LSF0204DPWR PI4ULS3V204LE
ADG3245BRUZ-REEL7 ADG3123BRUZ ADG3245BRUZ ADG3246BCPZ ADG3308BCPZ-REEL ADG3233BRJZ-REEL7
ADG32233BRMZ